



# Fast Recovery Diodes (Hockey PUK Version), 350 A



DO-200AA

### FEATURES

- High power FAST recovery diode series
- 1.0  $\mu$ s to 2.0  $\mu$ s recovery time
- High voltage ratings up to 2500 V
- High current capability
- Optimized turn-on and turn-off characteristics
- Low forward recovery
- Fast and soft reverse recovery
- Press PUK encapsulation
- Case style conform to JEDEC® DO-200AA
- Maximum junction temperature 125 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS  
COMPLIANT

PRODUCT SUMMARY	
$I_{F(AV)}$	350 A
Package	DO-200AA
Circuit configuration	Single diode

### TYPICAL APPLICATIONS

- Snubber diode for GTO
- High voltage freewheeling diode
- Fast recovery rectifier applications

MAJOR RATINGS AND CHARACTERISTICS					
PARAMETER	TEST CONDITIONS	VS-SD303C..C			UNITS
		S10	S15	S20	
$I_{F(AV)}$		350	350	350	A
	$T_{hs}$	55	55	55	°C
$I_{F(RMS)}$		550	550	550	A
	$T_{hs}$	25	25	25	°C
$I_{FSM}$	50 Hz	5770	5770	5770	A
	60 Hz	6040	6040	6040	
$I^2t$	50 Hz	166	166	166	kA <sup>2</sup> s
	60 Hz	152	152	152	
$V_{RRM}$	Range	400 to 1000	1200 to 1600	2000 to 2500	V
$t_{rr}$		1.0	1.5	2.0	$\mu$ s
	$T_J$	25	25	25	°C
$T_J$		-40 to 125	-40 to 125	-40 to 125	

### ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS				
TYPE NUMBER	VOLTAGE CODE	$V_{RRM}$ , MAXIMUM REPETITIVE PEAK AND OFF-STATE VOLTAGE V	$V_{RSM}$ , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	$I_{RRM}$ MAXIMUM AT $T_J = 125$ °C mA
VS-SD303C..S10C	04	400	500	35
	08	800	900	
	10	1000	1100	
VS-SD303C..S15C	12	1200	1300	
	14	1400	1500	
	16	1600	1700	
VS-SD303C..S20C	20	2000	2100	
	25	2500	2600	



FORWARD CONDUCTION					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum average forward current at heatsink temperature	$I_{F(AV)}$	180° conduction, half sine wave Double side (single side) cooled		350 (175)	A
				55 (75)	°C
Maximum RMS current	$I_{F(RMS)}$	25 °C heatsink temperature double side cooled		550	
Maximum peak, one-cycle, non-repetitive forward current	$I_{FSM}$	t = 10 ms	No voltage reappplied	5770	A
		t = 8.3 ms			
		t = 10 ms	100 % $V_{RRM}$ reappplied	4850	
		t = 8.3 ms		5080	
Maximum $I^2t$ for fusing	$I^2t$	t = 10 ms	No voltage reappplied	166	kA <sup>2</sup> s
		t = 8.3 ms			
		t = 10 ms	100 % $V_{RRM}$ reappplied	117	
		t = 8.3 ms		107	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 to 10 ms, no voltage reappplied		1660	kA <sup>2</sup> √s
Low level value of threshold voltage	$V_{F(TO)1}$	(16.7 % $\times \pi \times I_{F(AV)} < I < \pi \times I_{F(AV)}$ , $T_J = T_J$ maximum)		1.14	V
High level value of threshold voltage	$V_{F(TO)2}$	(I $> \pi \times I_{F(AV)}$ , $T_J = T_J$ maximum)		1.63	
Low level of forward slope resistance	$r_{f1}$	(16.7 % $\times \pi \times I_{F(AV)} < I < \pi \times I_{F(AV)}$ , $T_J = T_J$ maximum)		1.14	mW
High level of forward slope resistance	$r_{f2}$	(I $> \pi \times I_{F(AV)}$ , $T_J = T_J$ maximum)		0.77	
Maximum forward voltage drop	$V_{FM}$	$I_{pk} = 1100$ A, $T_J = 25$ °C; $t_p = 10$ ms sinusoidal wave		2.26	V

RECOVERY CHARACTERISTICS								
CODE	MAXIMUM VALUE AT $T_J = 25$ °C	TEST CONDITIONS			TYPICAL VALUES AT $T_J = 125$ °C			
	$t_{rr}$ AT 25 % $I_{RRM}$ (μs)	$I_{pk}$ SQUARE PULSE (A)	dI/dt (A/μs)	$V_r$ (V)	$t_{rr}$ AT 25 % $I_{RRM}$ (μs)	$Q_{rr}$ (μC)	$I_{rr}$ (A)	
S10	1.0	750	25	- 30	2.4	52	33	
S15	1.5				2.9	90	44	
S20	2.0				3.2	107	46	

THERMAL AND MECHANICAL SPECIFICATIONS					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum operating temperature range	$T_J$			- 40 to 125	°C
Maximum storage temperature range	$T_{Stg}$			- 40 to 150	
Maximum thermal resistance, junction to heatsink	$R_{thJ-hs}$	DC operation single side cooled		0.16	K/W
		DC operation double side cooled		0.08	
Mounting force, ± 10 %				4900 (500)	N (kg)
Approximate weight				70	g
Case style		See dimensions - link at the end of datasheet		DO-200AA	

$\Delta R_{thJ-hs}$ CONDUCTION						
CONDUCTION ANGLE	SINUSOIDAL CONDUCTION		RECTANGULAR CONDUCTION		TEST CONDITIONS	UNITS
	SINGLE SIDE	DOUBLE SIDE	SINGLE SIDE	DOUBLE SIDE		
180°	0.010	0.011	0.008	0.008	$T_J = T_J$ maximum	K/W
120°	0.012	0.013	0.013	0.013		
90°	0.016	0.016	0.018	0.018		
60°	0.024	0.024	0.025	0.025		
30°	0.042	0.042	0.042	0.042		

**Note**

- The table above shows the increment of thermal resistance  $R_{thJ-hs}$  when devices operate at different conduction angles than DC

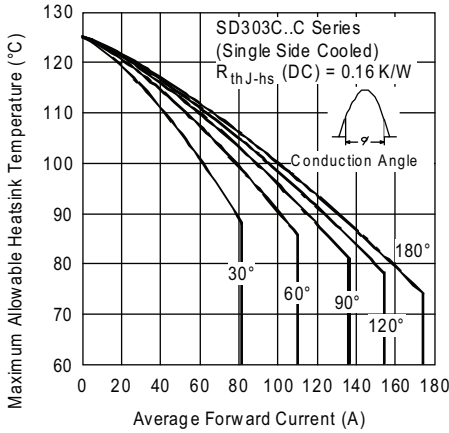


Fig. 1 - Current Ratings Characteristics

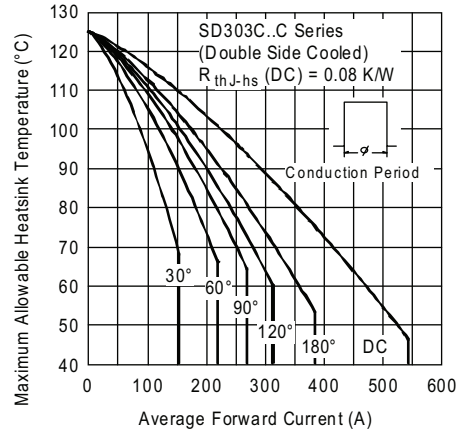


Fig. 4 - Current Ratings Characteristics

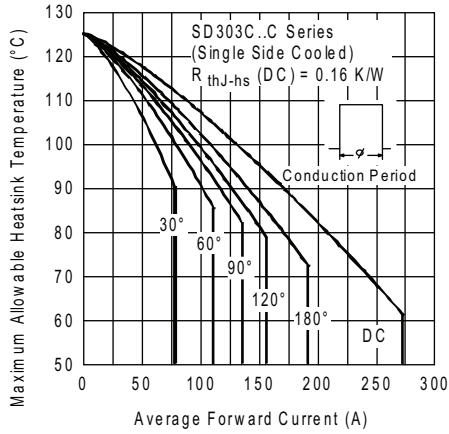


Fig. 2 - Current Ratings Characteristics

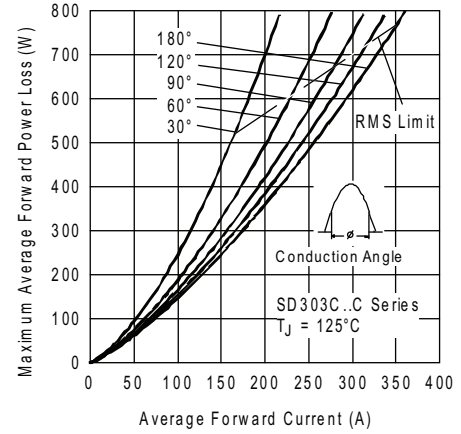


Fig. 5 - Forward Power Loss Characteristics

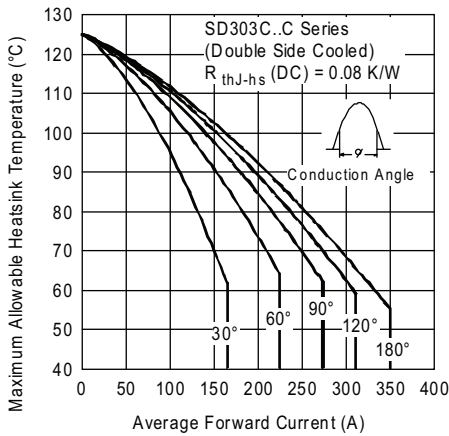


Fig. 3 - Current Ratings Characteristics

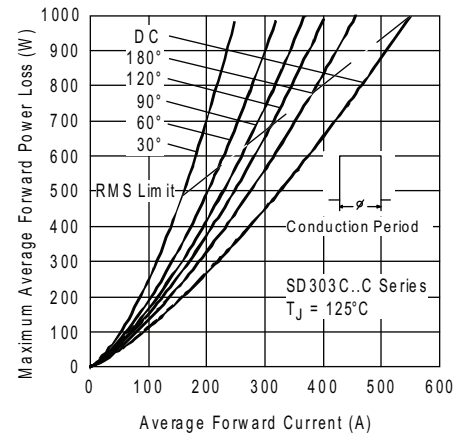


Fig. 6 - Forward Power Loss Characteristics

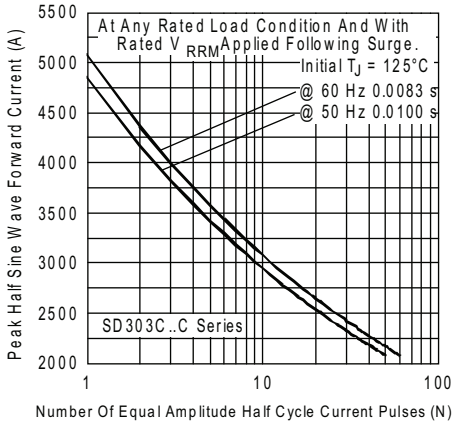


Fig. 7 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

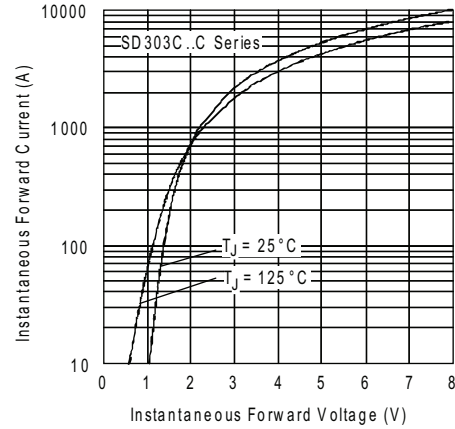


Fig. 9 - Forward Voltage Drop Characteristics

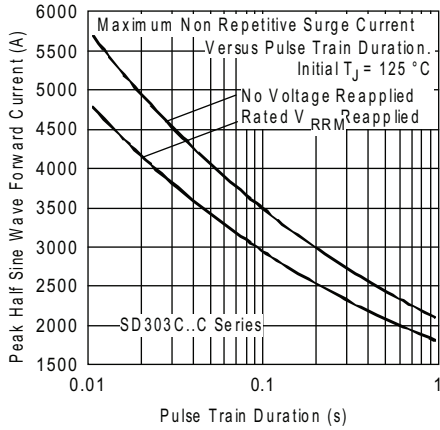


Fig. 8 - Maximum Non-Repetitive Surge Current Single and Double Side Cooled

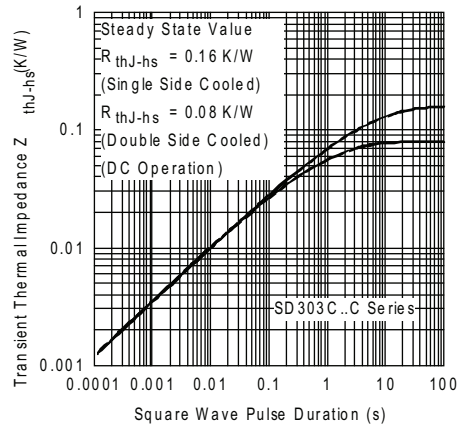


Fig. 10 - Thermal Impedance  $Z_{thj-hs}$  Characteristic

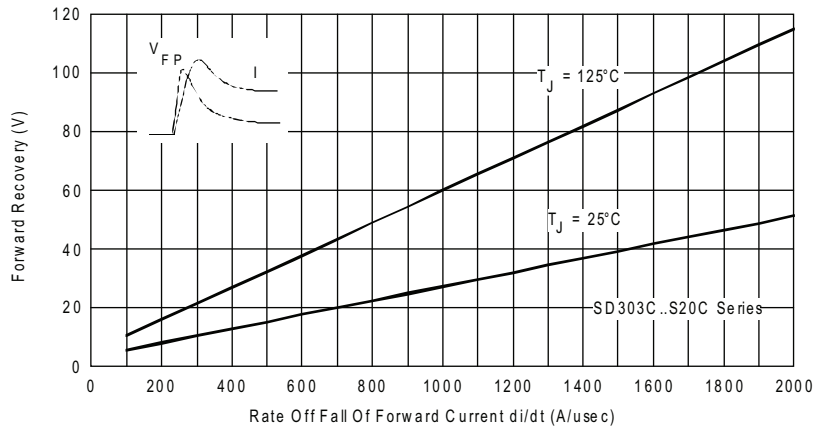


Fig. 11 - Typical Forward Recovery Characteristics

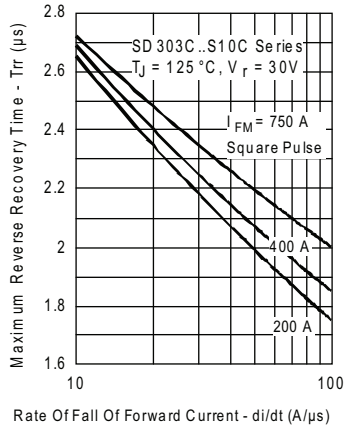


Fig. 12 - Recovery Time Characteristics

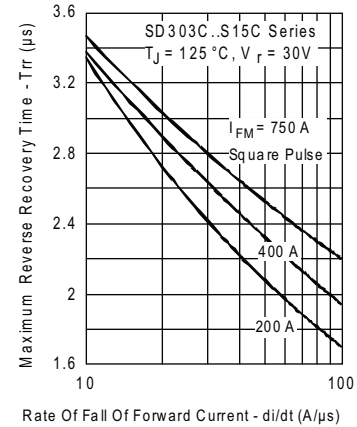


Fig. 15 - Recovery Time Characteristics

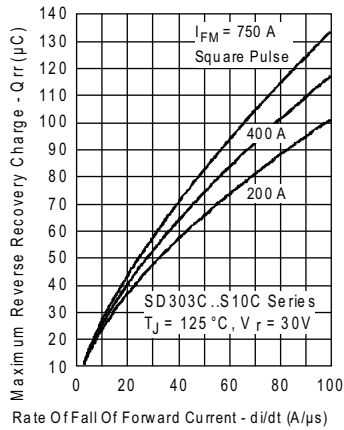


Fig. 13 - Recovery Charge Characteristics

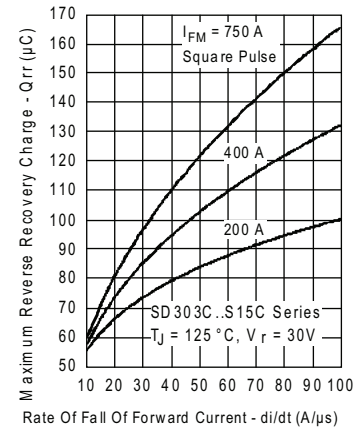


Fig. 16 - Recovery Charge Characteristics

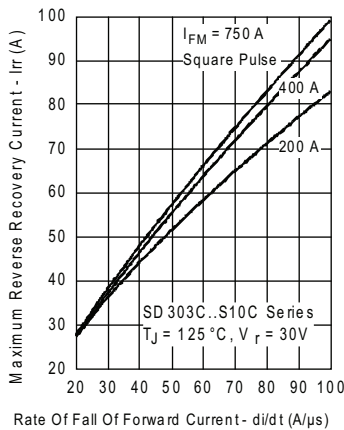


Fig. 14 - Recovery Current Characteristics

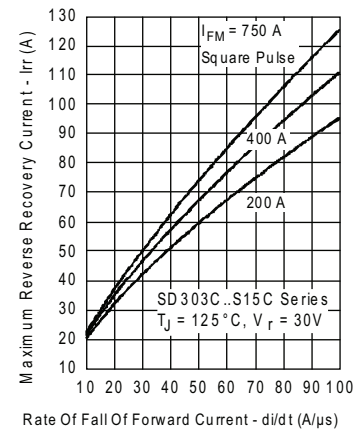


Fig. 17 - Recovery Current Characteristics

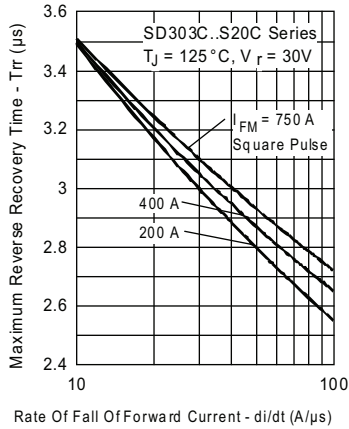


Fig. 18 - Recovery Time Characteristics

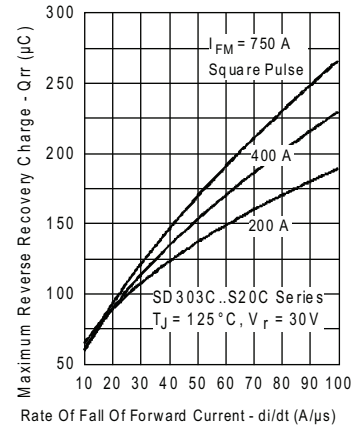


Fig. 19 - Recovery Charge Characteristics

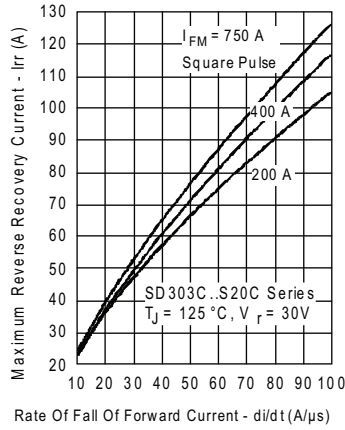


Fig. 20 - Recovery Current Characteristics

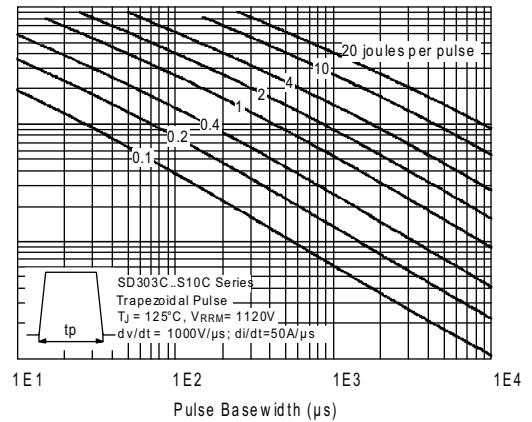
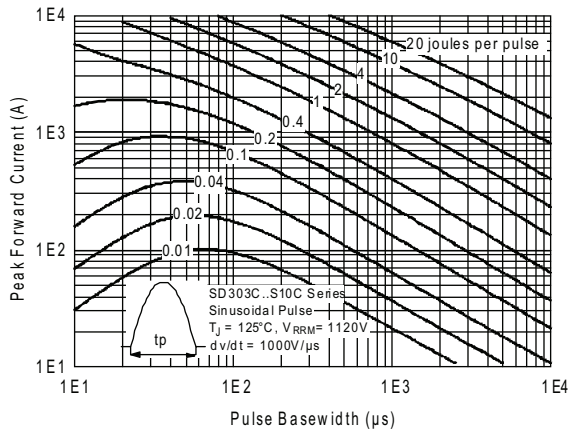


Fig. 21 - Maximum Total Energy Loss Per Pulse Characteristics

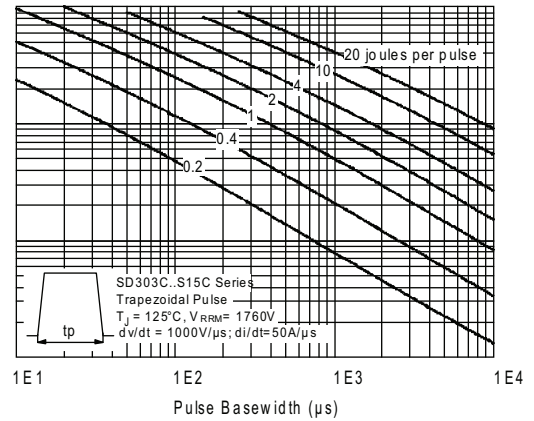
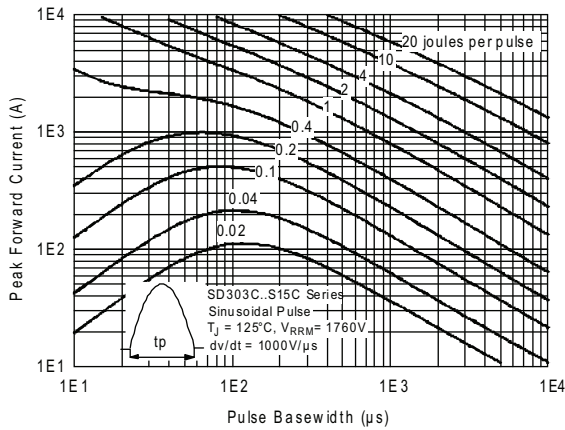


Fig. 22 - Maximum Total Energy Loss Per Pulse Characteristics

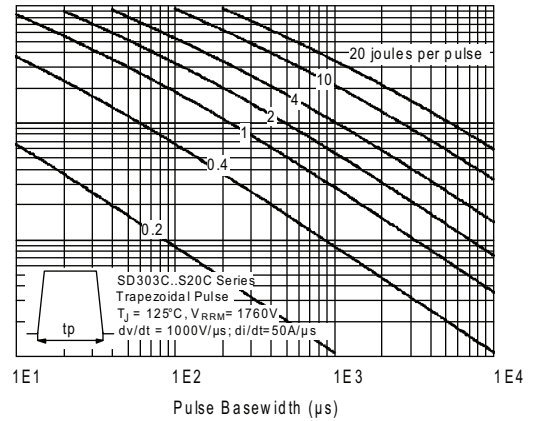
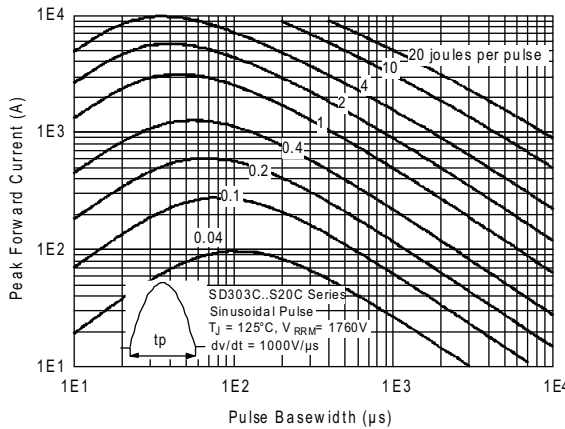


Fig. 23 - Maximum Total Energy Loss Per Pulse Characteristics

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>SD</b>	<b>30</b>	<b>3</b>	<b>C</b>	<b>25</b>	<b>S20</b>	<b>C</b>
	①	②	③	④	⑤	⑥	⑦	⑧

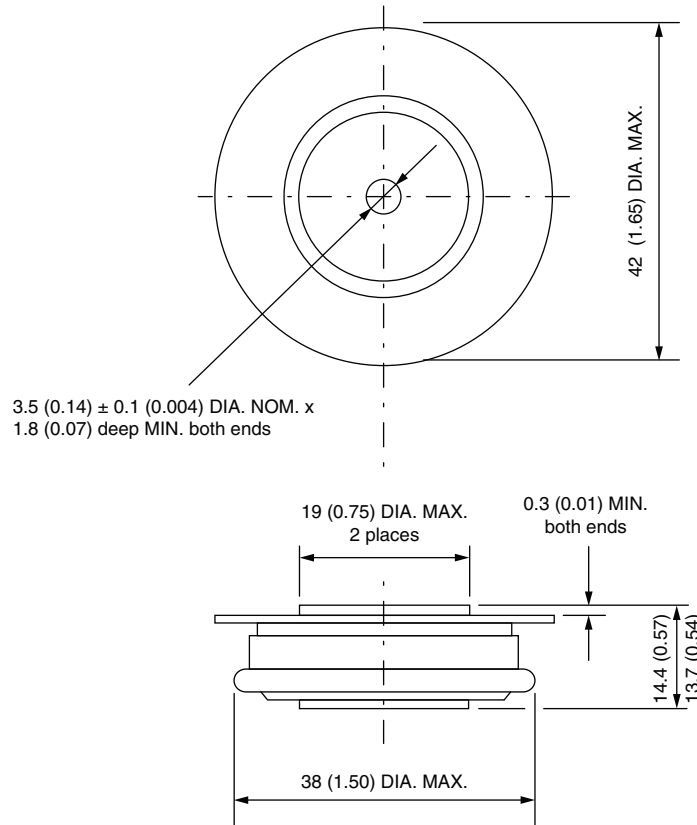
- 1** - Vishay Semiconductors product
- 2** - Diode
- 3** - Essential part number
- 4** - 3 = Fast recovery
- 5** - C = Ceramic PUK
- 6** - Voltage code x 100 =  $V_{RRM}$  (see Voltage Ratings table)
- 7** -  $t_{rr}$  code (see Recovery Characteristics table)
- 8** - C = PUK case DO-200AA

**LINKS TO RELATED DOCUMENTS**

Dimensions	<a href="http://www.vishay.com/doc?95248">www.vishay.com/doc?95248</a>
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## DO-200AA

**DIMENSIONS** in millimeters (inches)



Quote between upper and lower pole pieces has to be considered after application of mounting force (see Thermal and Mechanical Specifications)





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- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

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